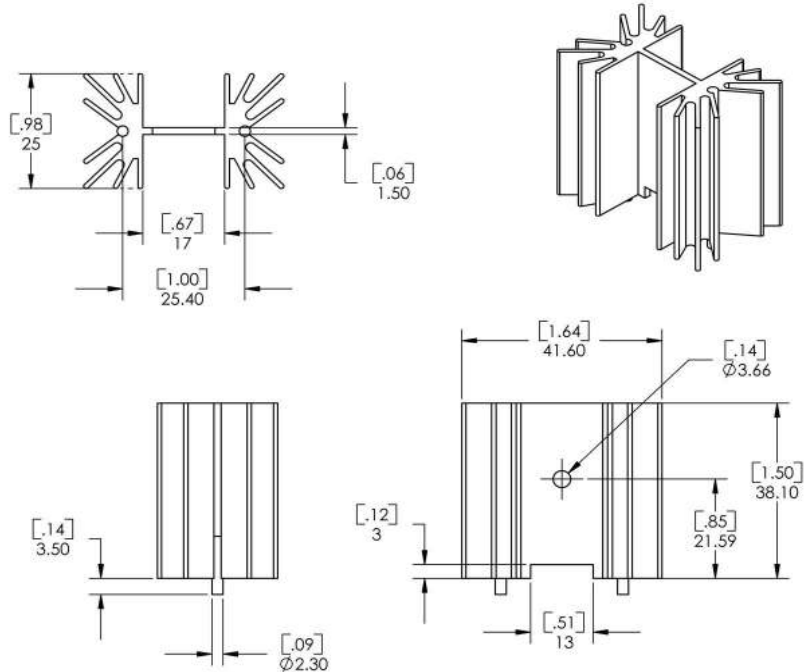
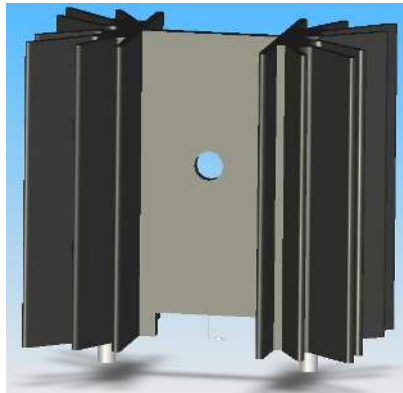


Board Level Heat Sinks



ThermaFlo

P/N: 411616B02500



TO-218, TO-220 & TO-247

PRODUCT SPECIFICATIONS

- Devices: TO-218, TO-220 & TO-247
- Size: 25.0 x 41.6 x 38.1MM
- Material: Aluminum
- Type: Extruded
- Finish: Black Anodized
- PCB Mounting: Solderable Pins
- Package: Bulk
- Accessories: Hardware & Thermal Interface Material

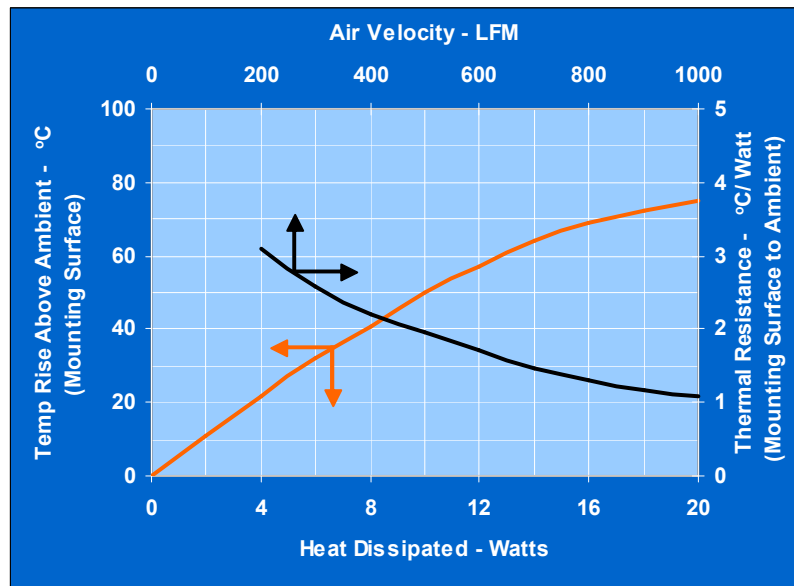
FEATURES & BENEFITS

- Hole for Device Attachment
- Dual Device Cooling Heat Sink
- Vertical Mounting via Solderable Pins
- RoHS Compliant



CUSTOMIZED HEATSINKS

- Specialized Plating
- Specialized Body Configurations
- Contact Applications Engineering



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